

Due to the high deformation capability and resilience of **harbus[®] HM** press-in contacts, they can be easily and repeatedly removed in case of repairs without impairment to their functioning.

harbus[®] HM press-in contacts are extremely versatile and offer a reliable electrical contact, therefore they are especially well suited for applications with these surfaces.

Please contact us for detailed test reports.

Benefits of press-in technology

- Thermal shocks associated with the soldering process and the risk of the board malfunction are avoided.
- No need for the subsequent cleaning of the assembled pcb's
- Unlimited and efficient processing of partially gold-plated pins for rear I/O - manual soldering is no longer necessary!

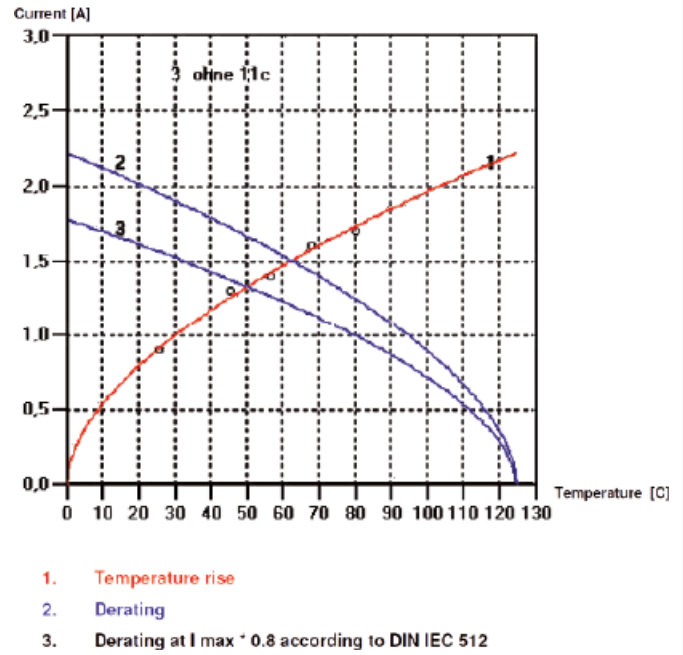
Recommended configuration of plated through holes

The press-in zone of the **harbus[®] HM** connectors is approved to be used with a plated through hole according EN 60352-5 with a diameter of 0.60 ± 0.05 mm (drilled hole 0.7 ± 0.02 mm).

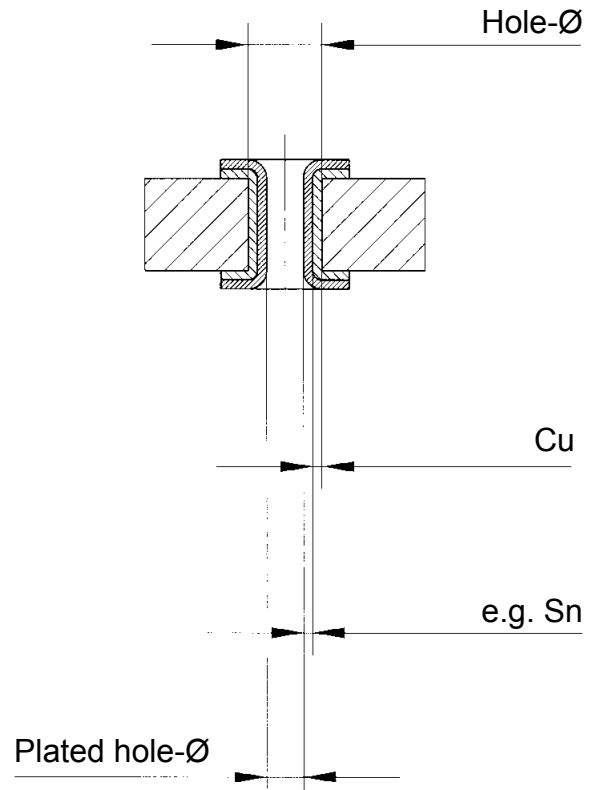
Based on our experiences regarding the production process of the PCB manufacturer, we recommend a plated through hole configuration like shown in the below spreadsheet. To achieve the recommended plated through hole diameter, it is important to specify especially the drilled hole diameter of 0.7 ± 0.02 mm to your PCB supplier.

<i>Tin plated PCB (HAL)</i>	Hole-Ø	0.7 ± 0.02 mm
	Cu	min. 25 µm
	Sn	max. 15 µm
	Plated hole-Ø	0.60-0.65 mm
<i>Chemical tin plated PCB</i>	Hole-Ø	0.7 ± 0.02 mm
	Cu	min. 25 µm
	Sn	min. 0.8 µm
	Plated hole-Ø	0.60-0.65 mm
<i>Au / Ni plated PCB</i>	Hole-Ø	0.7 ± 0.02 mm
	Cu	min. 25 µm
	Ni	3-7 µm
	Au	0.05-0.12 µm
	Plated hole-Ø	0.60-0.65 mm
<i>Silver plated PCB</i>	Hole-Ø	0.7 ± 0.02 mm
	Cu	min. 25 µm
	Ag	0.1-0.3 µm
	Plated hole-Ø	0.60-0.65 mm
<i>OSP copper plated PCB</i>	Hole-Ø	0.7 ± 0.02 mm
	Cu	min. 25 µm
	Plated hole-Ø	0.60-0.65 mm

PCB board thickness: ≥ 1.4 mm



Derating curve



Recommended configuration of plated through holes, valid for **harbus[®] HM**